EMBEDDED PROCESSING FEATURE

Scenes From the European Xilinx Developer Forum

Communities and the people that make them up are the foundation of society, from the local neighborhood BBQ club to the G7. Communities gather shared interests, topics, and goals, and foment growth and the creation of the next generation to carry on. The engineering community is no different, and the events held to support and nurture them are an important part of our industry.

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INDUSTRY 4.0 NEWS

Bosch Rexroth’s ctrlX AUTOMATION Presented as Most Open Automation Platform Available

Featuring an open software architecture as well as open choice of programming language and app technology, the ctrlX AUTOMATION platform from Bosch Rexroth removes boundaries between machine control systems, IT, and the Internet of Things (IoT).

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INDUSTRY 4.0 NEWS

Rittal and Eplan Launch Digital Information Management Solution for
Panel Building and Switchgear Manufacturing
Rittal and Eplan have developed a Digital Information Management (DIM), addressing panel building and switchgear manufacturing.
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INDUSTRY 4.0 NEWS
**Toradex Releases Over-The-Air Updates for TorizonCore under its Toradex Labs Innovation Brand**
Toradex announced the release of an experimental version of its Over-The-Air (OTA) solution under Toradex Labs.
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EMBEDDED HARDWARE NEWS
**New Low-End Performance Class for SMARC**
Congatec, a vendor of embedded computer boards and modules, introduces a new SMARC 2.0 Computer-on-Module with Arm Cortex-A53 based NXP Semiconductors i.MX 8M Nano processor.
Read more

EMBEDDED HARDWARE NEWS
**WAGO Expands TOPJOB S Terminal Blocks with New 2202 Series**
WAGO, an electrical interconnection, automation, and interface electronic company, announced the TOPJOB S new 2202 series which introduces a double-deck push-button terminal block with 15 degree vertical conductor entry.
Read more

SEMICONDUCTOR PACKAGING NEWS
**Smart Equipment Technology (SET) Introduces New Automatic Flip-Chip Bonder for Device Production**
Smart Equipment Technology, a supplier in die-to-die and die-to-wafer bonders, announced the release of NEO HB, an automatic flip-chip bonder designed for ?1 ?m 3? post-bonding accuracy, in stand-alone or full automatic mode (EFEM).
Read more

EE INDUSTRY NEWS
**2019 ACM Gordon Bell Prize Awarded to Eth Zurich Team for Developing Simulation That Maps Heat in Transistors**
ACM, the Association for Computing Machinery, named a six-member team from the Swiss Federal Institute of Technology (ETH) Zurich recipients of the 2019 ACM Gordon Bell Prize for their project, "A Data-Centric Approach to Extreme-Scale Ab initio Dissipative Quantum Transport Simulations."
Read more
Denchi Group to Expand its Engineering Capability with Additional Design Team in Heart of Cambridge Technology Cluster

Furthering their work in energy storage solutions, Denchi Group has announced an extension of its operations. It is opening a product development hub in St Ives, Cambridgeshire. This will complement Denchi’s engineering resources in Thurso, Scotland.

WEBCAST

Empowering Next-Generation Automotive Wireless Systems Using Advanced Test Solutions

Sponsored by: Anritsu
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EMBEDDED EXECUTIVE PODCAST

Embedded Executive: Chris Longstaff, VP of Product Management, Mindtech Global

Neural networks are complex. Mindtech makes tools that help create vision data sets for training these neural nets. In this week’s Embedded Executive podcast with Chris Longstaff, Vice President of Product Management at Mindtech, I discussed what an engineer would do with the data set once in-hand.

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